# **FORLINX**

#### **Product Specifications**

#### FET3506B-S/FET3506J-S SoM Series

#### FET3506J-S SoM

FET3506J - S SoM is based on the Rockchip RK3506J, a low-power, cost -effective processor for industrial automation and consumer electronics. It integrates 3 x ARM Cortex-A7 high-performance cores, embedded 2D hardware engine and display output engine to minimize CPU consumption to meet image display requirements; rich peripheral interfaces provide more application options. The SoM connects to the carrier board via edge connector for a more secure connection. It has undergone rigorous industrial environment testing in the Forlinx Embedded Laboratory, ensuring stable operation even in complex conditions. 10–15 year lifespan for long-term supply assurance.

#### **Product Features:**

- Edge connector, all pins are led out
- 22nm advanced process
- Display interfaces: MIPI DSI, RGB
- Rich industrial bus interfaces: RMII, CAN-FD, FLEXBUS, DSMC etc
- DSMC can be used to extend PSRAM, FPGA communication
- RM\_IO enables matrix configuration for pin functions.



NAND storage SoM; eMMC version is different from the figure

3×A7+1×M0	22nm	35×44mm
CRU	Process Technology	Compact size
Up to 1.6GHz	2×CAN-FD	Industrial grade
Main Frequency	CAN	-40 °C ∼ + 85 °C

#### ■ SoM Basic Parameters

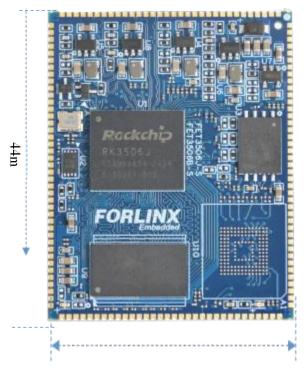
Processor		Rockchip RK3506J	Rockchip RK3506B					
		3 × Cortex-A7, up to 1.6GHz	3× CortexA7@1.5Gz 1× Cortex-M0					
	ARM:	1 × Cortex-M0						
	NPU:	No						
	GPU:	2D GPU						
	VPU:	No						
RAM		256MB/512MB DDR3	/					
ROM		256MB Nand Flash/8GB eMMC	/					
Operating Temperatu	re	-40°C ~+85°C	/					
Working V	oltage	DC 5V	DC 5V					
Connection	ı	Stamp hole (146 pins in total, pin center spacing 1mm)						

# SoM Function Parameters

Function	Quantity	Parameter							
MIPI DSI	≤1	Supports 1 x 2-lane MIPI Display Serial	Built-in VOP controller,						
		Interface with a speed of 1.5 Gbps per lane.	supporting only 1 x						
RGB	≤1	Supports RGB888 24-bit, with resolution up to 1280x1280@60Hz.	display output at a time.	RGB, FLEXBUS, and					
FLEXBUS	≤1	Supports 1 x flexible parallel FLEXBUS inter IO switching.	face, enabling high-speed	DSMC interfaces are multiplexed, allowing					
DSMC	≤1	Supports the DSMC data bus for PSRAM and FPGA can be expanded through the DSMC in	opports the DSMC data bus for PSRAM and FPGA communication.  GA can be expanded through the DSMC interface, with master mode selected at a time.  porting ×8 and ×16 data bits, and slave mode supporting ×8 data bits.						
USB 2.0	2	Supports 2 x high-speed USB 2.0 ports, with	1 x USB supporting OTG.						
SDMMC	≤1	Supports 1x SDIO, 4 bits; the eMMC version	SoM does not have this int	erface.					
Ethernet	2	$2 \times RMII$ , $10/100$ -Mbps, supporting both full-	-duplex and half-duplex ope	erations					
CAN-FD	2	Supports CAN2.0 and CAN-FD							
SPI	3	SPI0/SPI1 support both serial master and slav serial slave mode only.	e modes, configurable by s	oftware; SPI2 supports					
UART	≤6	Supports 6 x serial communication interfaces,	with UART0 serving as th	e debug serial port.					
I2C	3	Supports both 7-bit and 10-bit address modes, as well as master and slave modes, with a maximum speed of up to 1Mbit/s.							
Audio	/	4 × SAI(TX 1Lane/RX 1Lane ×2, TX 4Lane/ 1 × 4ch PDM 1×SPDIF TX/RX 1×Audio ADC 2 ×Audio DSM	4 × SAI(TX 1Lane/RX 1Lane ×2, TX 4Lane/RX 1Lane × 1, TX 1Lane/RX 4Lane × 1) 1 × 4ch PDM 1×SPDIF TX/RX 1×Audio ADC						
FSPI	≤1	Supports 1 x FSPI interface. By default, the S supports system startup.	oM is connected to the SPI	NAND FLASH, which					
SARADC	≤4		0-bit resolution, with a speed up to 1MS/s, and an input voltage range of 0~1.8V. ARADC0 is related to the boot-up sequence pins, while SARADC1 is multiplexed for recovery						
PWM	≤11	Supports 12 x PWM interfaces, with 1 x alreauser use.	Supports 12 x PWM interfaces, with 1 x already occupied by the SoM, leaving 11 available for						
JTAG	≤1	Supports JTAG SWD interface debugging, m	ultiplexed with the debug se	erial port UART0 pins.					
TOUCH KEY	≤8	Supports 8 x TOUCH KEY							
GPIO	≤76	GPI STO, GPO STO, among them, the six pins MIPI_DPHY_DSI_TX_D0N/D0P/D1N/D1P/CLKN/CLKP can only be used as General Purpose Outputs (GPOs).							

Note: The parameters in the table are hardware design or theoretical CPU values.

# Appearance and Dimensions





35mm

Note: PCB thickness is 1.2mm, the total height of the PCBA is 2.3mm, and the dimensional tolerance is  $\pm 0.2$ mm.

### Software Support:

OS	Linux 6.1.84					
Flashing Method	USB OTG					

#### Product Material List

\*More product information will be provided gradually after the product launch.

# Order Model List

<b>Specification Model</b>	SoM	CPU Clock	RAM	ROM	Temperature Range	Supply
FET3506J- S+15256SN256IAxx: xx	3×A7+1×M0	Up to 1.6GHz	256MB	256MB Nand Flash	-40°C ~ +85°C	R&D
FET3506J- S+15512SE8GIBxx: xx	3×A7+1×M0	Up to 1.6GHz	512MB	8GB eMMC	-40°C ~ +85°C	R&D
FET3506J- S+151GSE8GIxxx: xx	3×A7+1×M0	Up to 1.6GHz	1GB	8GB eMMC	-40°C ~ +85°C	Plan

### ■ SoM Naming Rule

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1 A 1	1 R I	1 _ 1	$\Gamma$	1 + 1	1 D 1	1 F I	1 F I			J	11 • 1	IKI	111
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Field	Field Description	Value	Description
	Product line	FET	Folinx Embedded SoM
A	identification	FL	Folinx Embedded All-in-one Panel

В	CPU	3506J	RK3506J
-	Segment identification	-	
C	Connection	S	Edge Connector
+	Segment identification	+	Following this identification, there is the configuration parameter section.
D	Maximum CPU	16	1.6 GHz
	Clock	15	1.5 GHz
		256	256MB
Е	RAM Capacity	512	512MB
E	(Unit: Byte)	1G	1GB
		2G	2GB
T. C. I. DOMET		SN	Nand Flash
F	Single ROM Type	SE	eMMC
		256	256MB
G	Single ROM	8G	8GB
	Capacity(U nit: Byte)	16G	16GB
		С	0 to 70°C Industrial Grade
Н	Operating	Е	-20 to 80 °C Wide Temperature Range
	Temperature	Ι	-40 to 85°C Industrial Grade
I	Configuration No.	A~Z	If D-H field values are identical across products, they are treated the same and sorted by release time in ascending order.
		10	V1.0
J	PCB Version	11	V1.1
		XX	Vx.x
:	Separator	:	This symbol is followed by the internal identification of the manufacturer, which has no effect on the customer's use.
KL	Manufacturer's Internal Logo	xx	It is manufacturer's internal logo without influence on use.

# Function Parameters

Function	Quantity	Parameter							
MIPI DSI	1	Single channel output, 2Lane without adaptation screen.	It has a built-in VOP controller.						
RGB	1	Supports RGB888 24-bit, with resolution up to 1280x1280@60Hz.	Only one display output is supported at a time.						
USB OTG	1	Uses a Type-C connector with master-slave dip switch selection for d	ownloading and flashing.						
USB 2.0	2	Supports 2 x high-speed USB 2.0 Type-A connectors.							
TF Card	1	1 x SDIO interface for external TF card, multiplexed with the SoM's on the SPI NAND version of the SoM.	1 x SDIO interface for external TF card, multiplexed with the SoM's eMMC pins, only available on the SPI NAND version of the SoM.						
4G	1	1 x mini PCIe connector for an external 4G module, using a USB 2.0	interface.						
Wi-Fi	1	1 W. E. o Di							
Bluetooth	1	1 x Wi-Fi & Bluetooth module RTL8723DU, using a USB 2.0 interfa	ice.						
Ethernet	2	Supports 2 x10/100 Mbps Ethernet ports with RMII interface.							
Audio	1	x four-segment audio jack, including 1 x dual-channel headphone output and 1 x MIC input, plus x additional onboard MIC.							
CAN-FD	2	Supports CAN and CAN-FD with isolation and protection.							

RS485	1	Supports 1 x RS485 with isolation and protection.
FSPI	1	Multiplexed with the SoM's SPI NAND Flash pins, default empty soldering.
RTC	1	I2C interface, onboard an RTC chip and button battery holder.
DEBUG	1	USB to serial converter for outputting debugging information, Type-C connector.
JTAG	1	Led out through a header pin, supporting JTAG interface debugging, multiplexed with the debug serial port pins.
KEY	6	Reset Maskrom VOL+, VOL- MENU ESC

Note: The parameters in the table are hardware design or theoretical CPU values.

